

# Overview of TUL-DMCS Projects and MicroTCA.4 Developments

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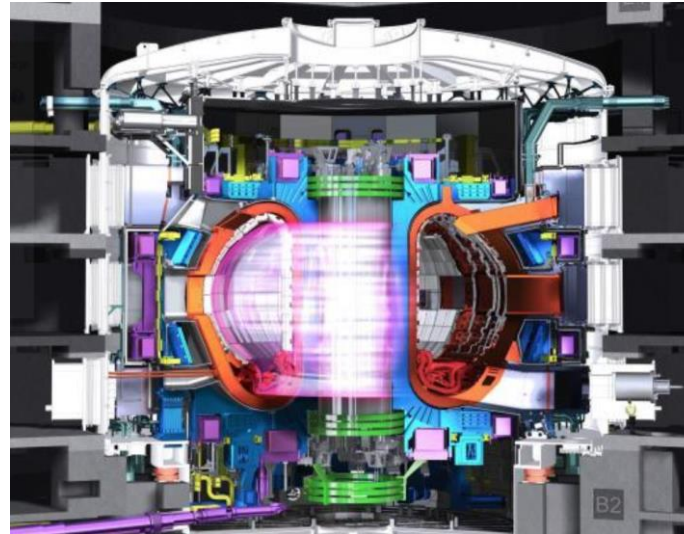
# Agenda

- Image Acquisition and Processing with MicroTCA.4
  - Image Processing for Machine Protection and Control
- Smart MMC and RMC solution for xTCA systems
- Basic-AMC
- High-power piezo driver for European Spallation Source Accelerator

# Fusion Projects - Plasma Diagnostics

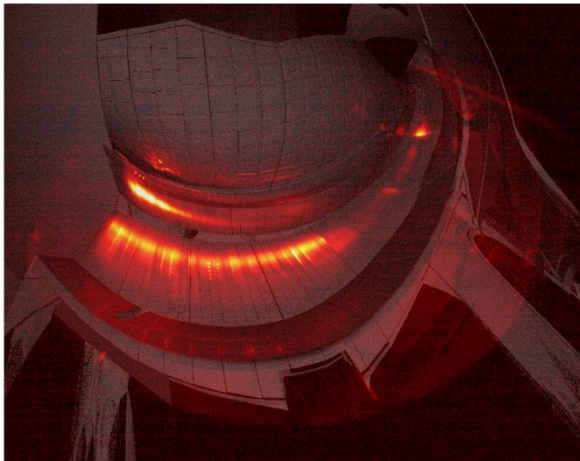
- Works since 2010
- Applications:
  - ITER
  - IPP/W7-X

➤ **A. Winter**  
**Thu 8/12, 9:45**

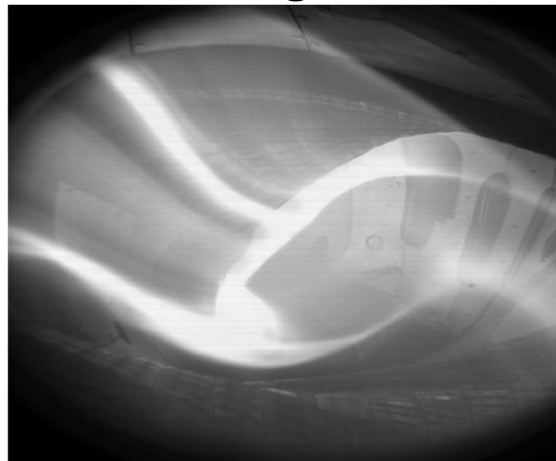


ITER Tokamak

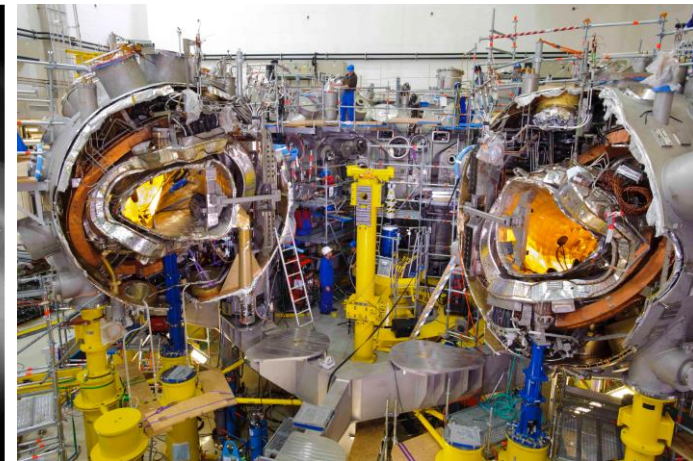
IR Diagnostics



VIS Diagnostics

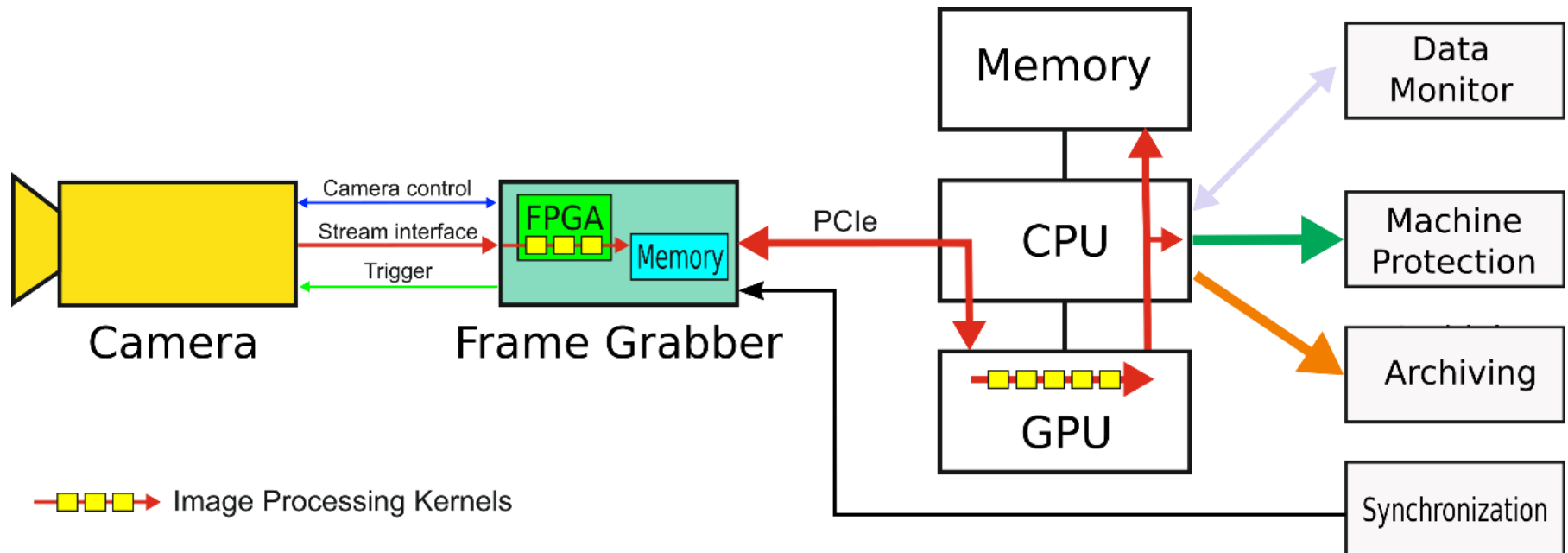


W7-X Stellarator

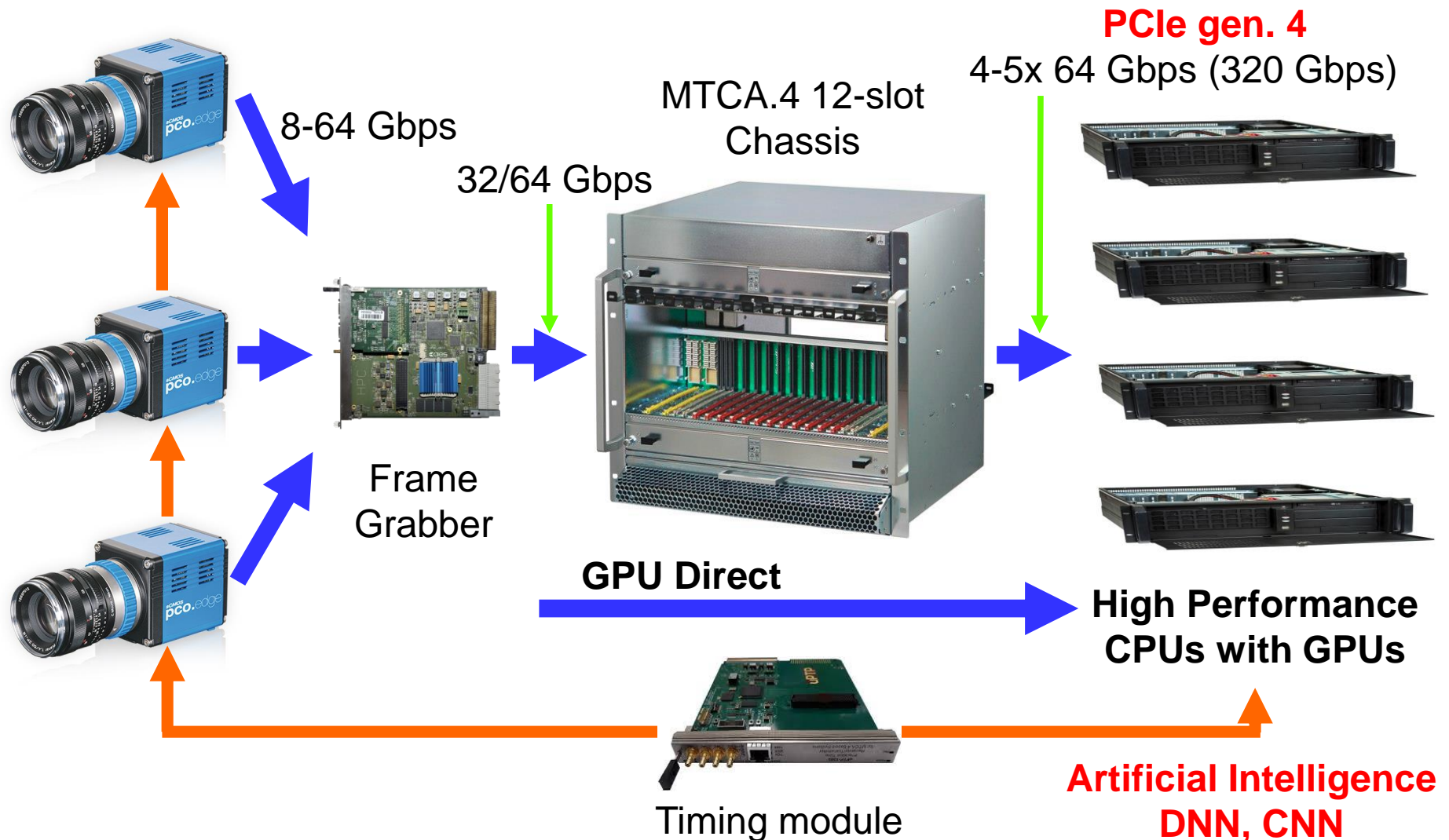


# Imaging Diagnostics – Image Acquisition and Processing

- ◆ Camera provides 1 or **more streams** of images
- ◆ **Frame grabber** configures camera, start and stop DAQ
- ◆ All devices are **synchronised** with machine (each frame includes timestamp)
- ◆ **All operations must work in real-time (hard real-time system)**
- ◆ Developed **hardware/software** should be compatible with **MicroTCA.4 subsystems**



# Image Acquisition and Processing with MicroTCA.4





## Hardware is Available

- ✓ **Camera Link** 2.04 Gb/s, 5.44 Gb/s, 6.8 Gb/s
- ✓ **Camera Link-HS** 2.4 Gbps / 128 Gbps
- ✓ **CoaXPress 2.0**  $n \times 6.25/12.5 \text{ Gb/s}$  ( $n=4 \rightarrow 25/50 \text{ Gb/s}$ )
- ✓ **1 GigE Vision** 800 Mb/s
- ✓ **10/25 GigE Vision** 10/25 Gbps
- ✓ **IEEE1394/Fire Wire** 0.4 Gb/s (1394a) or 0.8 Gb/s (1394b)
- ✓ **HD-SDI** 1.45 Gb/s (max. 2.9 Gbps)



SCD Hercules (CL)



Emergent HR-12000M camera with  
10 GigE Vision interface



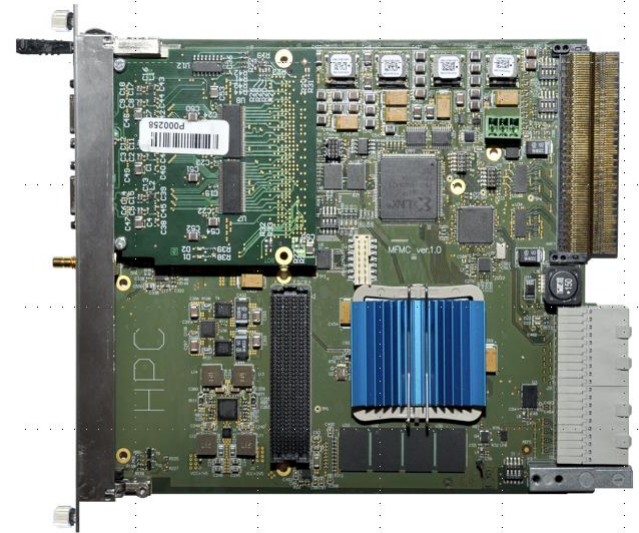
# FMC Carrier Modules

Frame grabber is composed of:

- ◆ Hardware we have
  - ◆ FMC carrier
    - ◆ Artix 7 FPGA (<6.5 Gb/s)
    - ◆ Zynq US+ (<16 Gbps)
    - ◆ **Kintex US+ (<32 Gb/s)**
- ◆ FMC modules supporting various camera interfaces (8 standards)

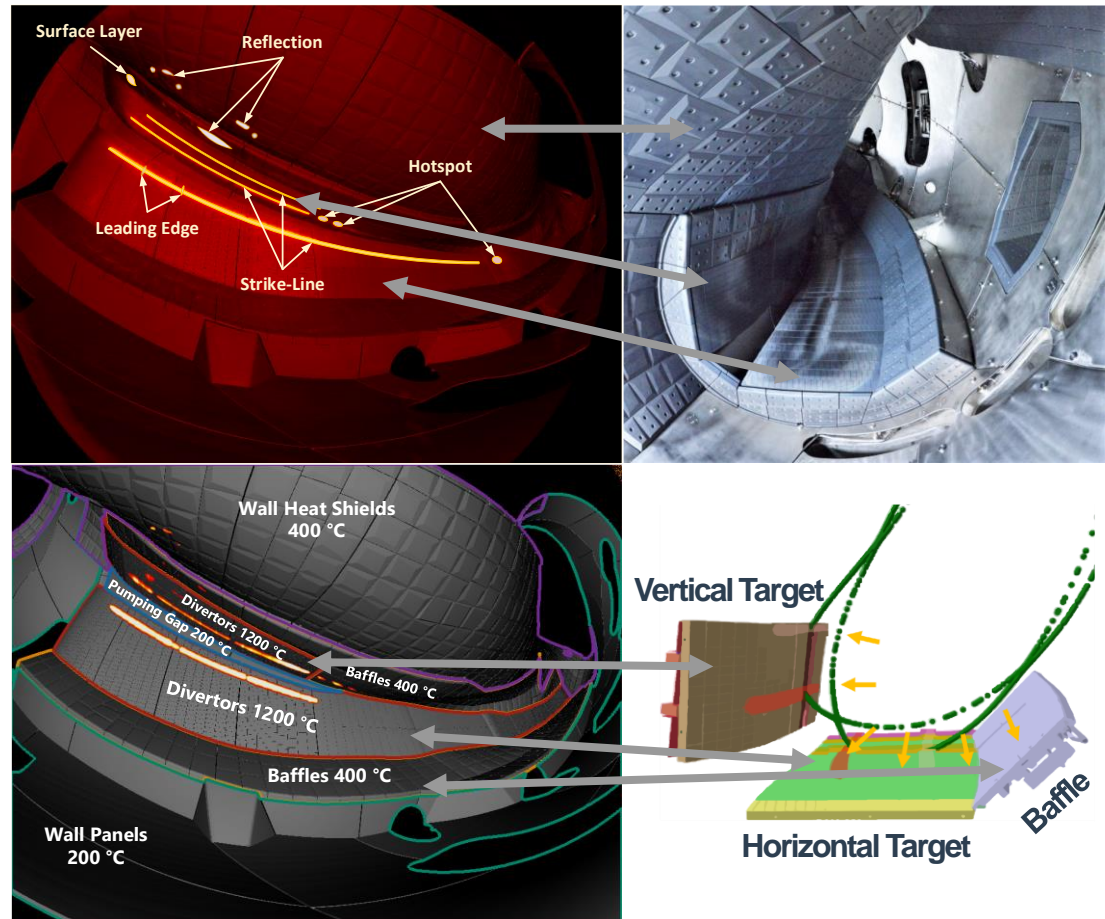
Software support:

- ◆ **IP cores** for selected **camera interfaces**
- ◆ Common Linux driver (**dmtcauni**)
- ◆ **Dedicated camera library** (GenlCam)
- ◆ Real-time processing software
- ◆ Algorithms (FPGA, CPU, GPU)
- ◆ **We move from development phase to maintenance**



# Machine Protection with Imaging Systems

- **Thermal Overload**  
**Detection** system is being prepared for the OP2.1 campaign in Wendelstein 7-X
- **Protect Plasma Facing Components (PFCs)** from thermal overloads with infrared (IR) cameras
- **Trigger the Fast Interlock System (FIS)** to terminate a discharge when a thermal overload is anticipated
- **W7-X has 12 IR cameras**, and **10 divertor units** are monitored

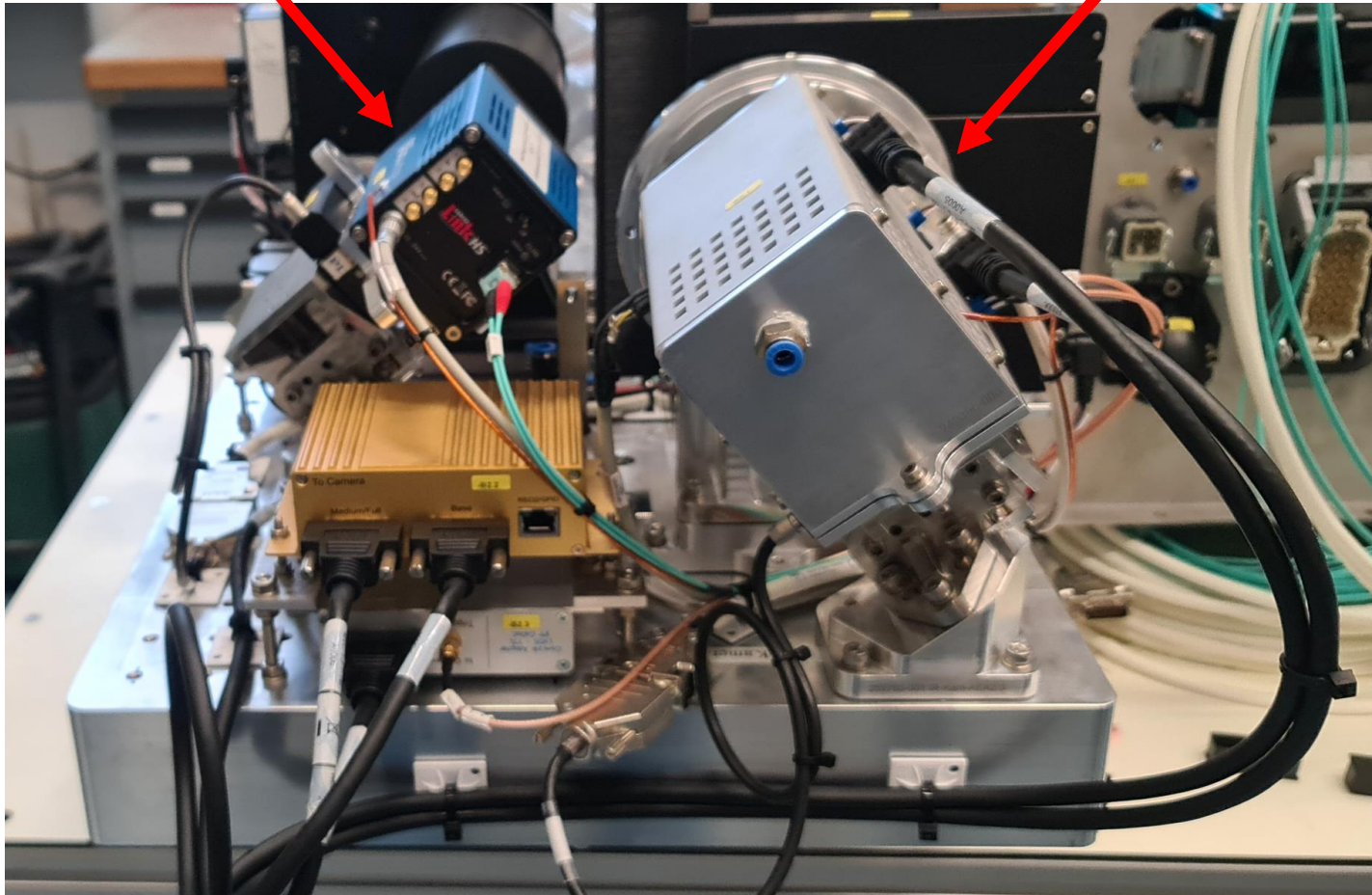




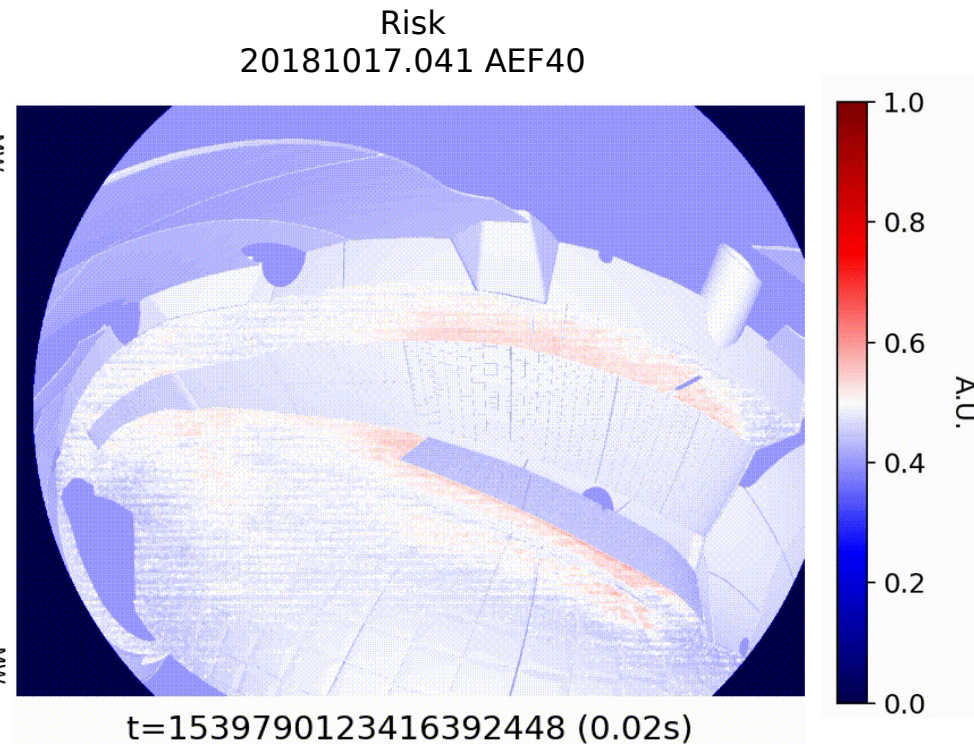
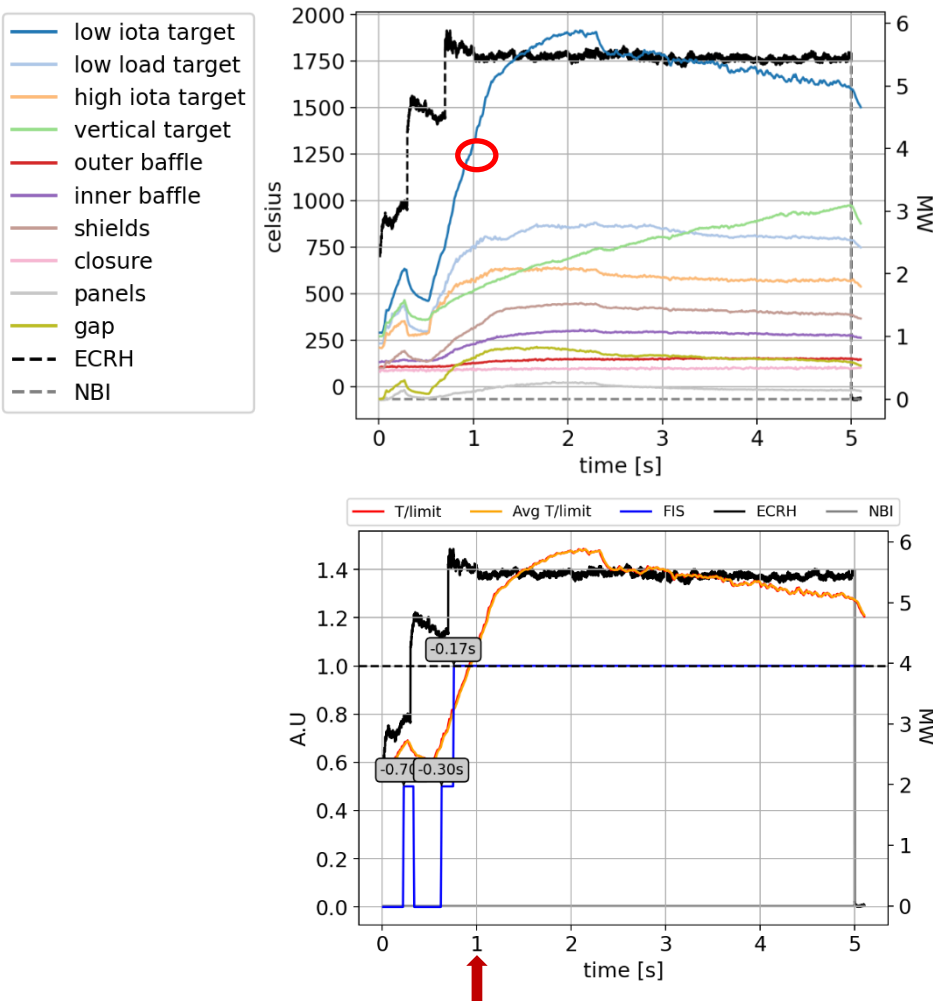
# Cameras Assembled in Endoscope

PCO Edge 5.5, CLHS

SCD Hercules, CL



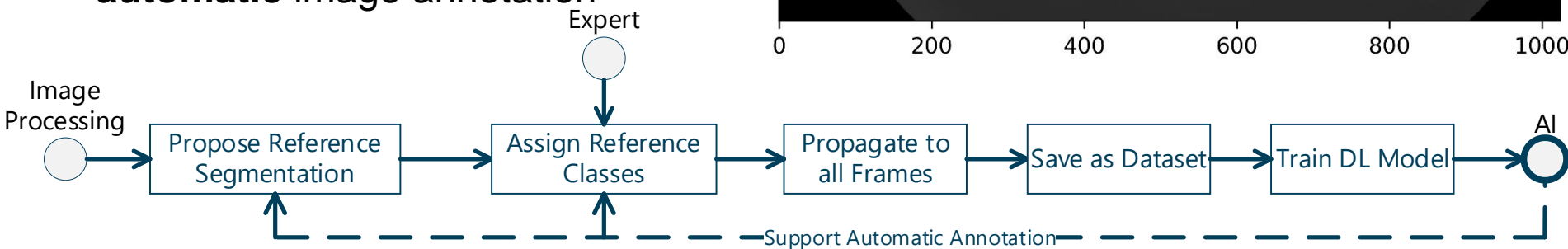
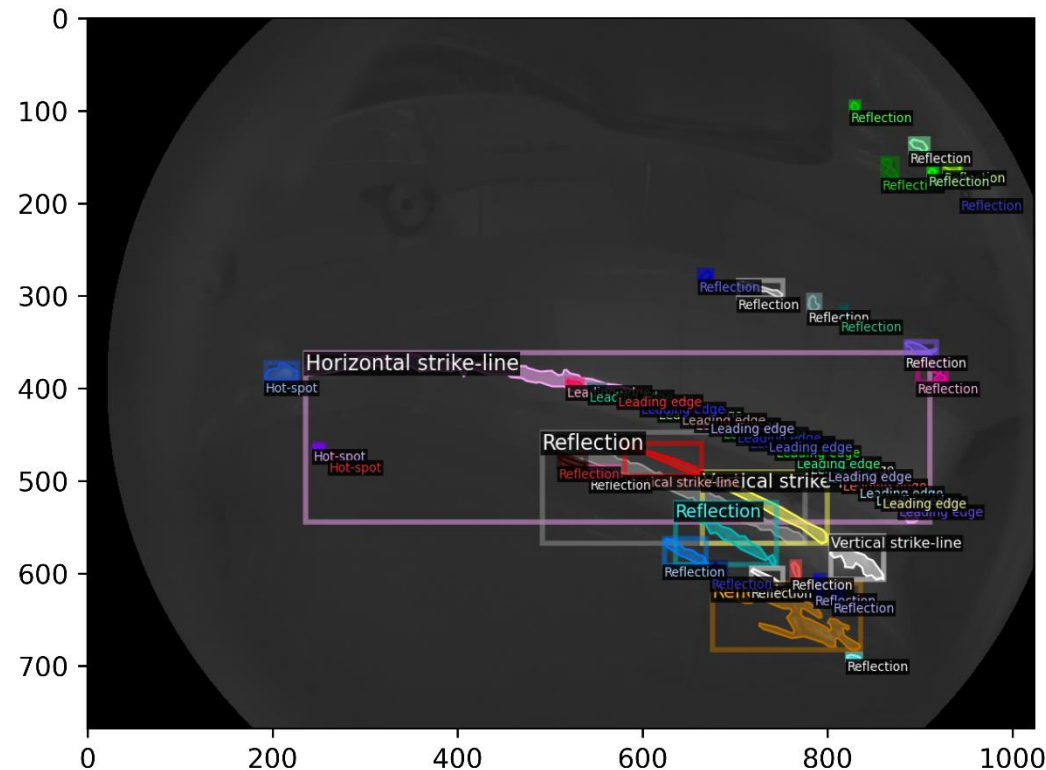
# Thermal Overload Detection (TOD)



*Low iota target overload at ~1 s,  
anticipated 170 ms before*

# Thermal Event Detection and Classification

- **Deep Learning** for instance segmentation (detection and classification) of **thermal events** in IR images
- Requires a substantial amount of **annotated data**
- Images are **complex** to annotate **manually** (100 frames per discharge second to annotate)
- Develop a method for **semi-automatic** image annotation



# Discharge Sequence Annotation

Annotated Image

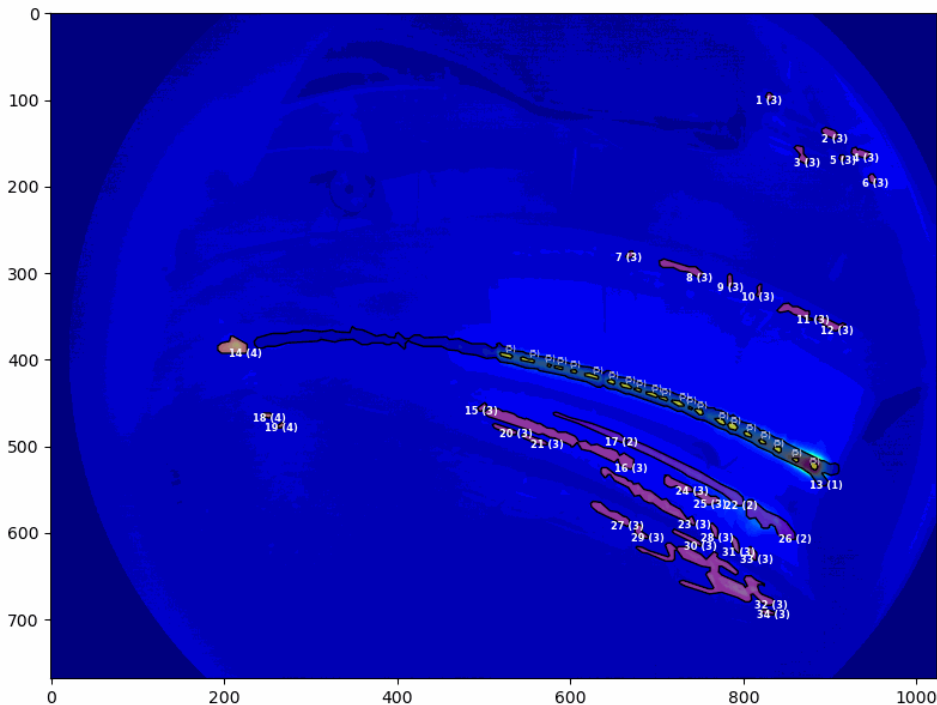
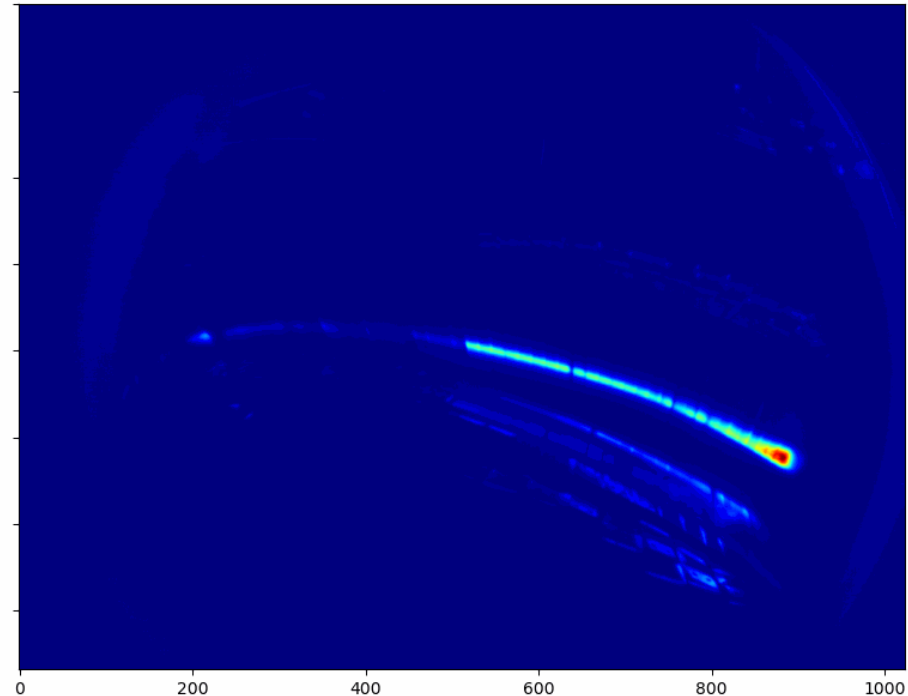


Image without Background



- 1: Horizontal strike-line
- 2: Vertical strike-line
- 3: Reflection

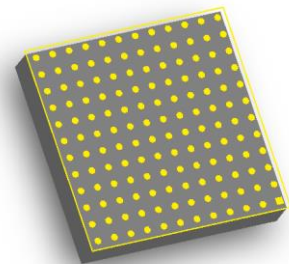
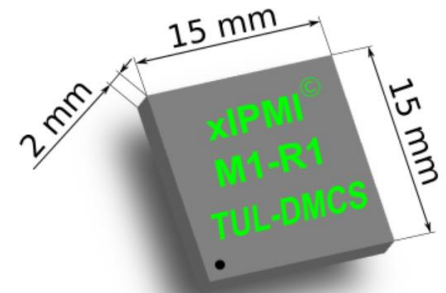
- 4: Hot-spot
- 5: Leading edge
- 6: UFO



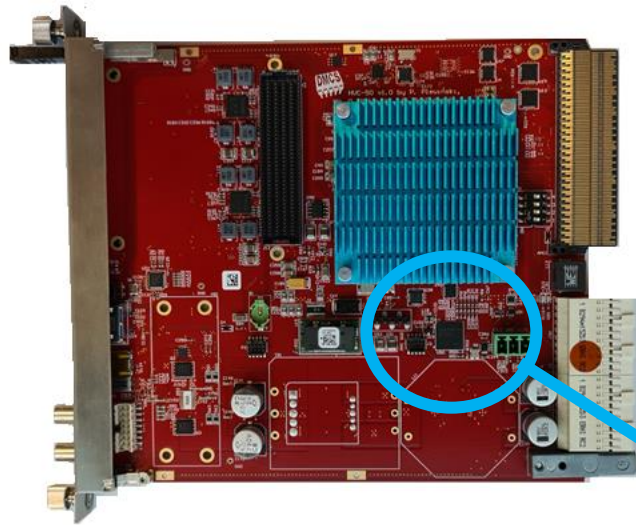
# Smart MMC and RMC solution for xTCA systems including FMC support

# Smart MMC and RMC solution for xTCA

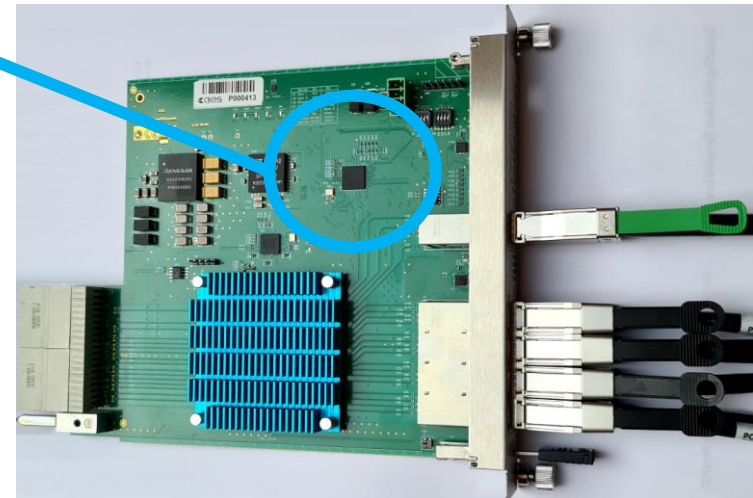
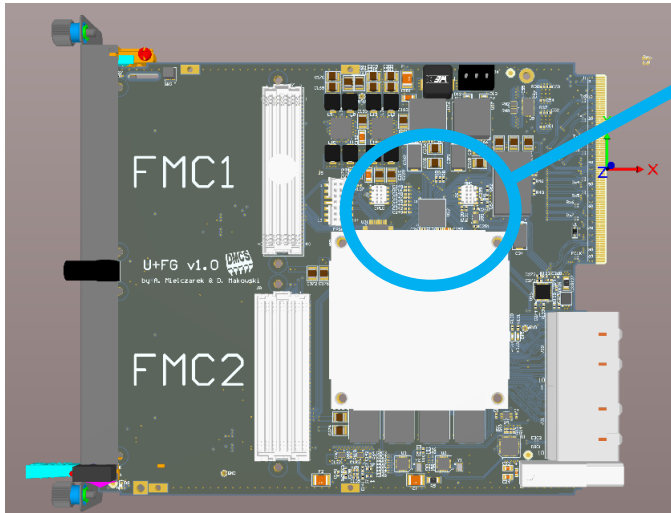
- TUL-DMCS works on **MMC/IPMC** solutions since 2006
- ASIC-like solution:
  - **Miniature size 15 mm x 15 mm x 2 mm**
  - **Cost-effective solution**
- Looking for solution for both:
  - **AdvancedTCA (Carrier and RTM)**
  - **MicroTCA (AMC, RTM)**
  - **Basic and Advanced versions**
- **ARM microcontroller**
  - 1 or 2 ARM cores
  - Low consumption power
  - Ready to be integrated with RTM
- **Programmable logic with up to 12 I2C interfaces**
- **Working of firmware and software**
  - Full HPM.1 support including **HPM.1 roll-back** (first time in MTCA.4 world)



# MicroTCA – MMC Implementations



MMC

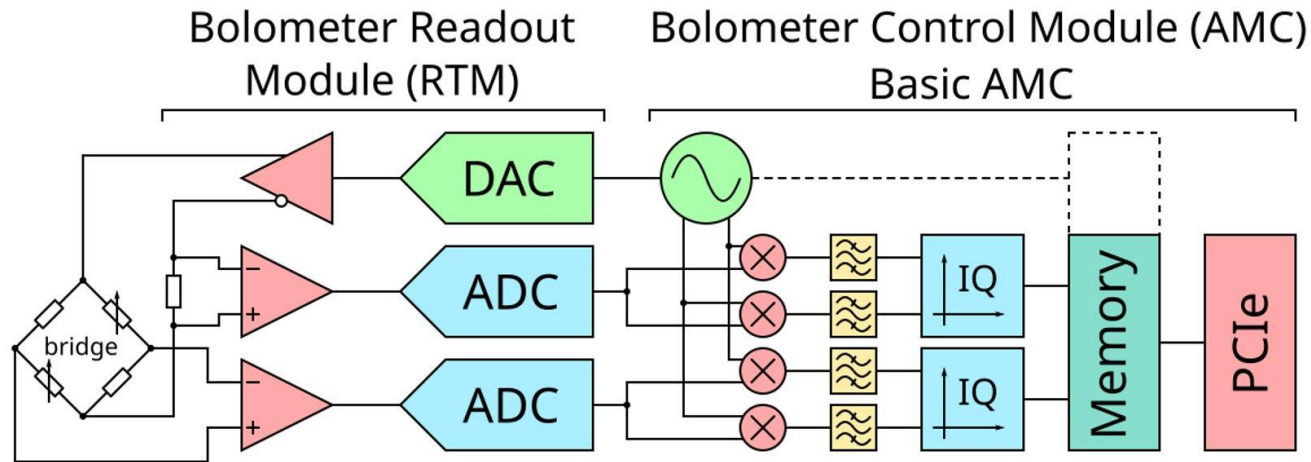


# Basic-AMC – the low-cost MicroTCA.4 Compliant Carrier Module

- See presentation on Wed 7/12, 16:45
- See presentation on Thu 8/12, 9:45



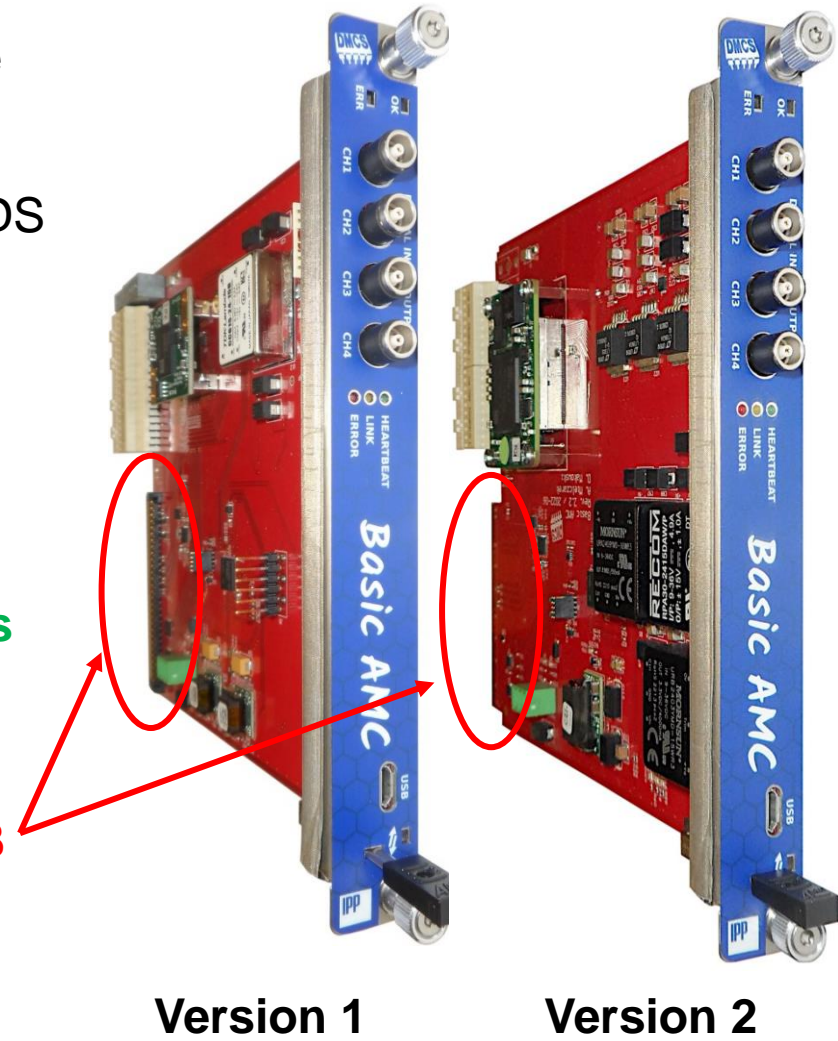
# Bolometer System for W7X



- Use MicroTCA.4 standard to build the system, cost-effective design
- Provides excitation signal for bolometer Wheatstone bridge
- Measure and digitally process signal from the Wheatstone bridge
- **Measurements used for real-time plasma control**
- Data acquisition and processing part **implemented as D-AMC**
- Analogue low-noise front end and **digitalisation part implemented as D-RTM**

## Basic-AMC Features

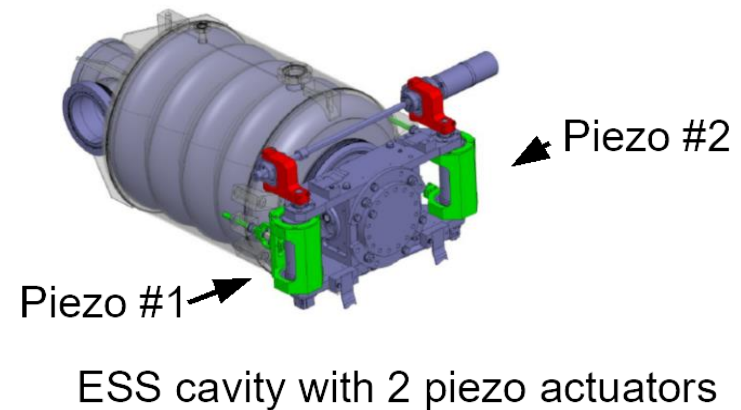
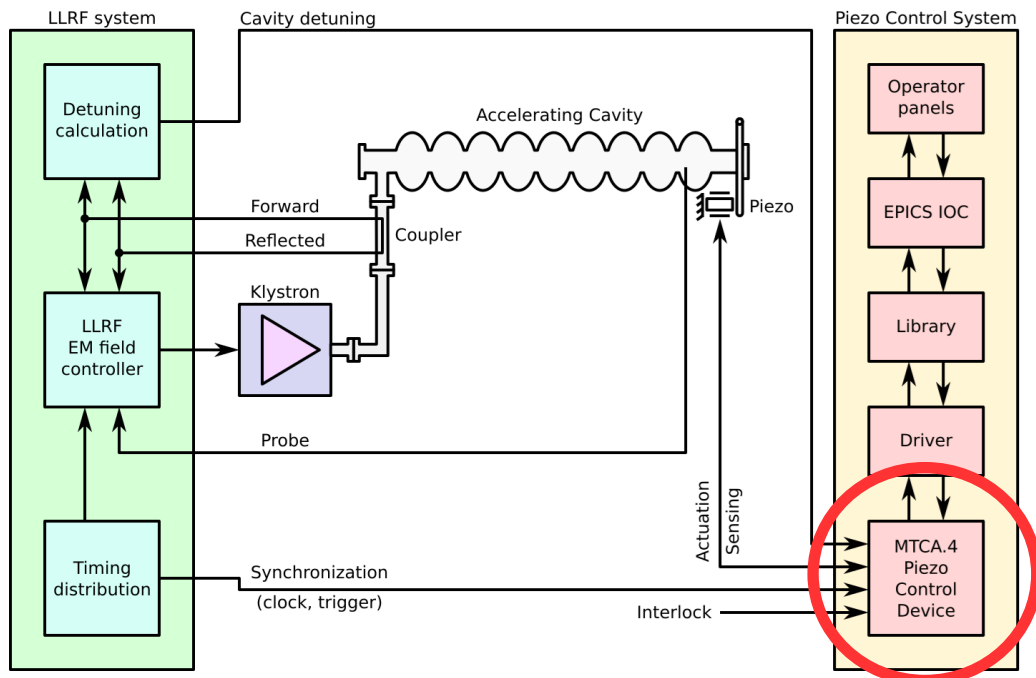
- Based on commercial Trenz FPGA module
- Offers multi-gigabit connectivity
- FPGA I/O signals on Zone 3 and three LVDS clocks
- Provide **voltages for analogue components** on RTM
- The PCB has only 6 metal layers, including two full ground planes
- **Pre-production succeeded (no problems detected)**
- **Production finished (ca. 55 modules)**
- **Problems with components (Harting/ITB connectors) – need to redesign PCB**
- **Final test next month...**



# High-power piezo driver for European Spallation Source Accelerator

## High Power Piezo Driver - Motivation

- This work is being done in frame of the Polish in-kind delivered by the **Polish Electronic Group (PEG)** within in-kind agreement signed between PEG and ESS on 2016-11-08, (together with Schedule AIK 8.2, signed 09.2017, ESS-0060409)
- Department of Microelectronics and Computer Science, Lodz University of Technology as a member of PEG consortium is responsible for piezo driver system delivery for elliptical cavities of ESS linac.





# MicroTCA.4 Workshop in 2017

High Power Piezo Driver Module for MicroTCA.4

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## Live Demo at TUL-DMCS Booth



**MicroTCA.4**  
for Industry and Research



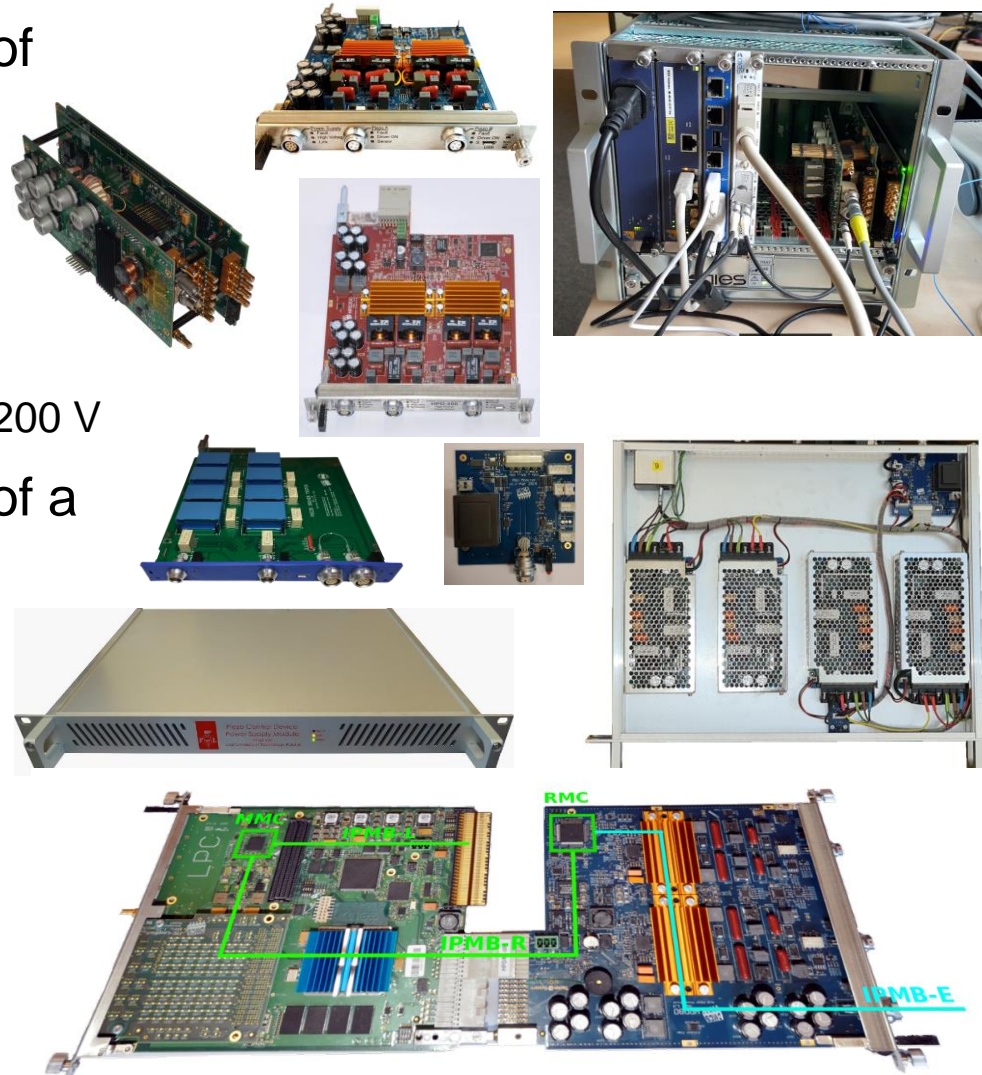
**Dariusz Makowski on behalf of DMCS Team**  
DESY, 7 December 2017



**Dariusz Makowski**  
11<sup>th</sup> MTCA Workshop, Dec. 8, 2022

# History...

- ◆ Developed and tested 3 versions of piezo driver (HPD)
  - ◆ Linear amplifier
  - ◆ PWM amplifier
  - ◆ Bipolar and unipolar variants
  - ◆ Various voltage ranges:  $\pm 100$  V,  $\pm 200$  V
- ◆ Developed and tested 2 versions of a dedicated Power Supply Module (PPSM)
- ◆ Finally agreed for:
  - ◆ HPD-200 ( $\sim \pm 190$  V,  $\sim 380$  Vpp)
  - ◆ PPSM-200 ( $\pm 100$  V)
- ◆ **Class-D amplifiers**



## Current Status

- ▶ Started mass production on beginning of 2022
  - ▶ HPD-200 (130 pieces)
  - ▶ PPSM-200 (130 pieces)
- ▶ Big problems with components availability
  - ▶ Components changed and PCBs redesigned
- ▶ Final production ongoing
  - ▶ **PPSM-200 (40 pieces manufacture), +90 under production**
  - ▶ **HPD-200 pre-production started, mass production in January'2023**
- ▶ Final tests and delivery to ESS

# Thank you for your attention